

PMEG100T050ELPE

100 V, 5 A low leakage current Trench MEGA Schottky barrier rectifier

3 December 2020

Product data sheet

1. General description

Trench Maximum Efficiency General Application (MEGA) Schottky barrier rectifier encapsulated in a CFP15B (SOT1289B) power and flat lead Surface-Mounted Device (SMD) plastic package.

2. Features and benefits

- Low forward voltage
- Low Q_{rr} and low I_{RM}
- · Low leakage current
- · High power capability due to clip-bonding technology
- · Small and flat lead SMD power plastic package
- AEC-Q101 qualified

3. Applications

- High efficiency DC-to-DC conversion
- · Automotive LED lighting
- · Switch mode power supply
- · Freewheeling application
- Reverse polarity protection
- OR-ing

4. Quick reference data

Table 1. Quick reference data

| Symbol | Parameter | Conditions | | Min | Тур | Max | Unit |
|--------------------|-------------------------|--|-----|-----|-----|-----|------|
| I _{F(AV)} | average forward current | δ = 0.5; square wave; f = 20 kHz; T _{sp} \leq 163 °C | | - | - | 5 | Α |
| V _R | reverse voltage | T _j = 25 °C | | - | - | 100 | V |
| V _F | forward voltage | I _F = 5 A; pulsed; T _j = 25 °C | [1] | - | 750 | 810 | mV |
| I _R | reverse current | V _R = 100 V; pulsed; T _j = 25 °C | [1] | - | 0.4 | 2.5 | μA |
| | | V _R = 100 V; pulsed; T _j = 125 °C | [1] | - | 0.6 | 3 | mA |

^[1] Very short pulse, in order to maintain a stable junction temperature.



5. Pinning information

Table 2. Pinning information

| Pin | Symbol | Description | Simplified outline | Graphic symbol |
|-----|--------|-------------|--------------------|----------------|
| 1 | А | anode | 5 | ⊬ PA A |
| 2 | Α | anode | | A aaa-009063 |
| 3 | K | cathode | 2 (20710000) | aaa-009003 |
| | | | CFP15B (SOT1289B) | |

6. Ordering information

Table 3. Ordering information

| Type number | Package | | | | | | | |
|-----------------|---------|--|----------|--|--|--|--|--|
| | Name | Description | Version | | | | | |
| PMEG100T050ELPE | CFP15B | plastic, thermal enhanced ultra thin SMD package; 3 leads; 2.13 mm pitch; 5.8 x 4.3 x 0.95 mm body | SOT1289B | | | | | |

7. Marking

Table 4. Marking codes

| Type number | Marking code |
|-----------------|--------------|
| PMEG100T050ELPE | 100T |
| | L05E |

8. Limiting values

Table 5. Limiting values

In accordance with the Absolute Maximum Rating System (IEC60134).

| Symbol | Parameter | Conditions | | Min | Max | Unit |
|--------------------|-------------------------------------|---|-----|-----|------|------|
| V _R | reverse voltage | T _j = 25 °C | | - | 100 | V |
| I _F | forward current | δ = 1; T _{sp} ≤ 159 °C | | - | 7 | А |
| I _{F(AV)} | average forward current | δ = 0.5; square wave; f = 20 kHz; T _{sp} ≤ 163 °C | | - | 5 | А |
| I _{FSM} | non-repetitive peak forward current | t_p = 8.3 ms; half sine wave; $T_{j(init)}$ = 25 °C | | - | 100 | А |
| P _{tot} | total power dissipation | T _{amb} ≤ 25 °C | [1] | - | 1.66 | W |
| | | | [2] | - | 2.15 | W |
| Tj | junction temperature | | | - | 175 | °C |
| T _{amb} | ambient temperature | | | -55 | 175 | °C |
| T _{stg} | storage temperature | | | -65 | 175 | °C |

^[1] Device mounted on an FR4 Printed-Circuit Board (PCB), single-sided copper, tin-plated and standard footprint.

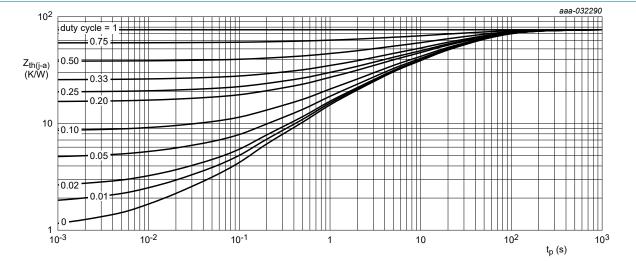
Device mounted on an FR4 PCB, single-sided copper, tin-plated, mounting pad for cathode 1 cm².

9. Thermal characteristics

Table 6. Thermal characteristics

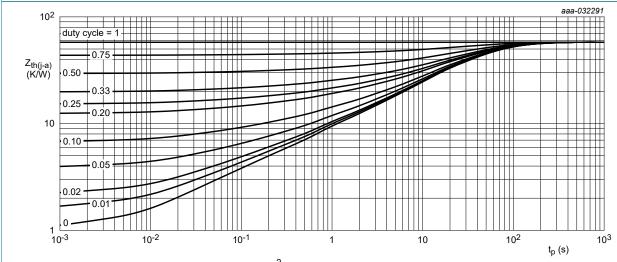
| Symbol | Parameter | Conditions | | Min | Тур | Max | Unit |
|-----------------------|--|-------------|---------|-----|-----|-----|------|
| R _{th(j-a)} | thermal resistance from | in free air | [1] [2] | - | - | 90 | K/W |
| junction to ambient | junction to ambient | | [1] [3] | - | - | 70 | K/W |
| R _{th(j-sp)} | thermal resistance from junction to solder point | | [4] | - | - | 7 | K/W |

- [1] For Schottky barrier diodes thermal runaway has to be considered, as in some applications the reverse power losses P_R are a significant part of the total power losses.
- [2] Device mounted on an FR4 PCB, single-sided copper, tin-plated and standard footprint.
- [3] Device mounted on an FR4 PCB, single-sided copper, tin-plated, mounting pad for cathode 1 cm².
- [4] Soldering point of cathode tab.



FR4 PCB, standard footprint

Fig. 1. Transient thermal impedance from junction to ambient as a function of pulse duration; typical values



FR4 PCB, mounting pad for cathode 1 cm²

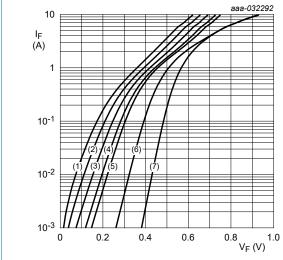
Fig. 2. Transient thermal impedance from junction to ambient as a function of pulse duration; typical values

10. Characteristics

Table 7. Characteristics

| Symbol | Parameter | Conditions | | Min | Тур | Max | Unit |
|-----------------|-------------------------------------|--|-----|-----|------|------|------|
| $V_{(BR)R}$ | reverse breakdown voltage | I _R = 1 mA; T _j = 25 °C | [1] | 100 | - | - | V |
| V _F | forward voltage | I _F = 0.5 A; pulsed; T _j = 25 °C | [1] | - | 460 | 560 | mV |
| | | I _F = 1 A; pulsed; T _j = 25 °C | [1] | - | 510 | 580 | mV |
| | | I _F = 2 A; pulsed; T _j = 25 °C | [1] | - | 580 | 650 | mV |
| | | I _F = 3 A; pulsed; T _j = 25 °C | [1] | - | 650 | 710 | mV |
| | | I _F = 5 A; pulsed; T _j = 25 °C | [1] | - | 750 | 810 | mV |
| | | I _F = 5 A; pulsed; T _j = -40 °C | [1] | - | 755 | 820 | mV |
| | | I _F = 5 A; pulsed; T _j = 125 °C | [1] | - | 620 | 690 | mV |
| | | I _F = 5 A; pulsed; T _j = 150 °C | [1] | - | 580 | 660 | mV |
| I _R | reverse current | V _R = 60 V; pulsed; T _j = 25 °C | [1] | - | 0.15 | 0.63 | μΑ |
| | | V_R = 100 V; pulsed; T_j = 25 °C | [1] | - | 0.4 | 2.5 | μΑ |
| | | V _R = 100 V; pulsed; T _j = 125 °C | [1] | - | 0.6 | 3 | mA |
| | | V _R = 100 V; pulsed; T _j = 150 °C | [1] | - | 2.3 | 12 | mA |
| C _d | diode capacitance | V _R = 1 V; f = 1 MHz; T _j = 25 °C | | - | 410 | - | pF |
| | | V _R = 10 V; f = 1 MHz; T _j = 25 °C | | - | 120 | - | pF |
| t _{rr} | reverse recovery time step recovery | $I_F = 0.5 \text{ A}; I_R = 0.5 \text{ A}; I_{R(meas)} = 0.1 \text{ A};$ $T_j = 25 \text{ °C}$ | | - | 12 | - | ns |
| | reverse recovery time ramp recovery | $dI_F/dt = 200 \text{ A/}\mu\text{s}; I_F = 6 \text{ A}; V_R = 26 \text{ V};$ $T_j = 25 ^{\circ}\text{C}$ | | - | 12 | - | ns |
| RM | peak reverse recovery current | $dI_F/dt = 200 \text{ A/s}; I_F = 6 \text{ A}; V_R = 26 \text{ V};$ $T_j = 25 \text{ °C}$ | | - | 1.3 | - | А |
| Q _{rr} | reverse recovery charge | | | - | 9.5 | - | nC |
| V_{FRM} | peak forward recovery voltage | $I_F = 0.5 \text{ A}$; $dI_F/dt = 20 \text{ A/µs}$; $T_j = 25 \text{ °C}$ | | - | 460 | - | mV |

^[1] Very short pulse, in order to maintain a stable junction temperature.



pulsed condition

(1) Tj = 175 °C

(2) Tj = 150 °C

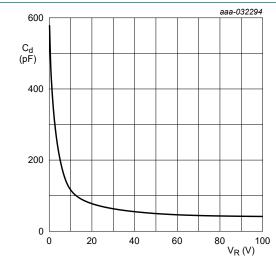
(3) Tj = 125 °C

(4) Tj = 100 °C

(5) Tj = 85 °C (6) Tj = 25 °C

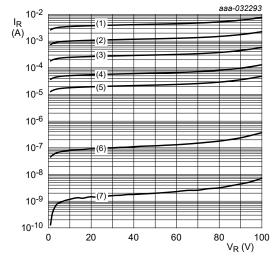
(7) Tj = -40 °C

Fig. 3. Forward current as a function of forward voltage; typical values



 $f = 1 MHz; T_{amb} = 25 °C$

Fig. 5. Diode capacitance as a function of reverse voltage; typical values



pulsed condition

(1) $T_i = 175 \,^{\circ}\text{C}$

 $(2) T_i = 150 °C$

(3) $T_i = 125 °C$

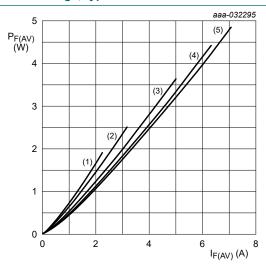
(4) $T_i = 100 °C$

 $(5) T_j = 85 ^{\circ}C$

(6) $T_j = 25 \,^{\circ}\text{C}$

 $(7) T_j = -40 ^{\circ}C$

Fig. 4. Reverse current as a function of reverse voltage; typical values



T_j = 100 °C

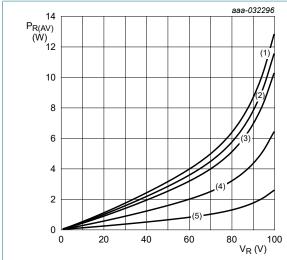
 $(1) \delta = 0.1$

 $(2) \delta = 0.2$

 $(3) \delta = 0.5$

(4) $\delta = 1$; DC

Fig. 6. Average forward power dissipation as a function of average forward current; typical values



 $T_j = 100 \, ^{\circ}C$

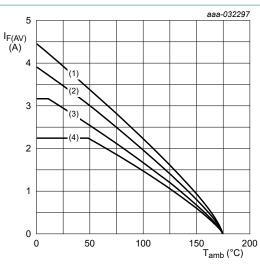
 $(1) \delta = 1; DC$

 $(2) \delta = 0.9$

 $(3) \delta = 0.8$ $(4) \delta = 0.5$

 $(5) \delta = 0.2$

Fig. 7. Average reverse power dissipation as a function of reverse voltage; typical values



FR4 PCB, standard footprint

T_i = 175 °C

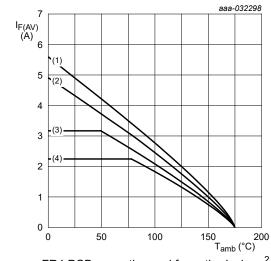
 $(1) \delta = 1$; DC

(2) $\delta = 0.5$; f = 20 kHz

(3) $\delta = 0.2$; f = 20 kHz

(4) $\delta = 0.1$; f = 20 kHz

Fig. 8. Average forward current as a function of ambient temperature; typical values



FR4 PCB, mounting pad for cathode 1 cm²

 $T_j = 175$ °C

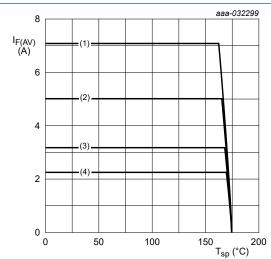
(1) $\delta = 1$; DC

(2) $\delta = 0.5$; f = 20 kHz

(3) $\delta = 0.2$; f = 20 kHz

(4) $\delta = 0.1$; f = 20 kHz

Fig. 9. Average forward current as a function of ambient temperature; typical values



Tj = 175 °C

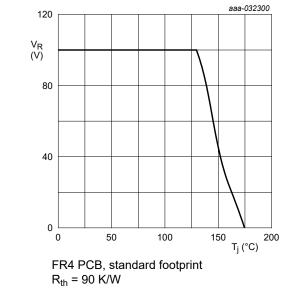
(1) δ = 1; DC

(2) δ = 0.5; f = 20 kHz

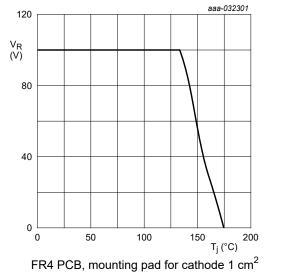
(3) $\delta = 0.2$; f = 20 kHz

(4) $\delta = 0.1$; f = 20 kHz

Fig. 10. Average forward current as a function of solder point temperature; typical values

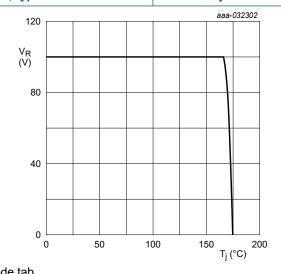


of junction temperature; typical values



 $R_{th} = 70 \text{ K/W}$





Soldering point of cathode tab

 $R_{th} = 7 \text{ K/W}$

Fig. 13. Derated maximum reverse voltage as a function of junction temperature; typical values

11. Test information

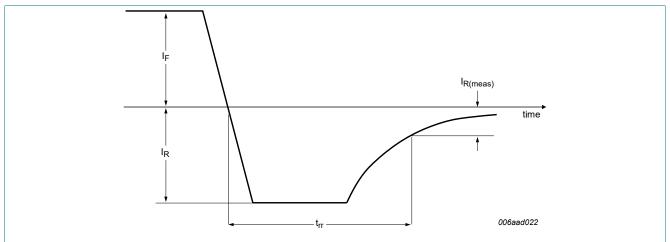


Fig. 14. Reverse recovery definition; step recovery

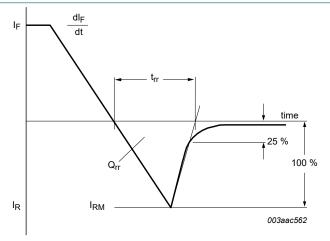


Fig. 15. Reverse recovery definition; ramp recovery

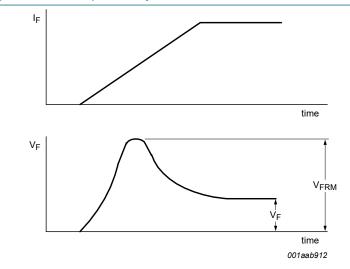
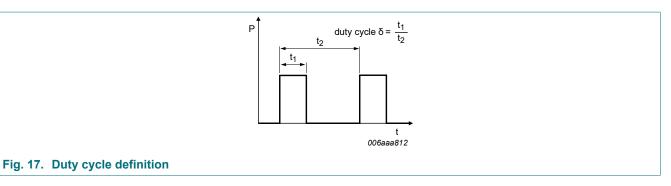


Fig. 16. Forward recovery definition



The current ratings for the typical waveforms are calculated according to the equations:

 $I_{F(AV)} = I_M \times \delta$ with I_M defined as peak current

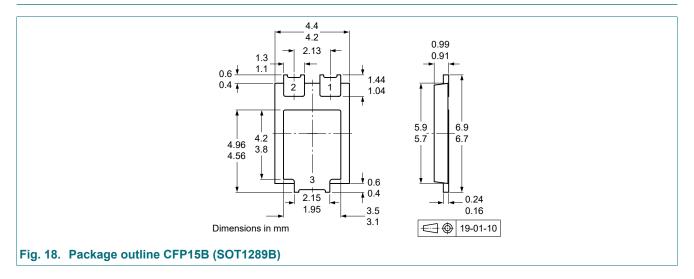
 $I_{RMS} = I_{F(AV)}$ at DC, and $I_{RMS} = I_M \times \sqrt{\delta}$

with $I_{\mbox{\scriptsize RMS}}$ defined as RMS current.

Quality information

This product has been qualified in accordance with the Automotive Electronics Council (AEC) standard Q101 - Stress test qualification for discrete semiconductors, and is suitable for use in automotive applications.

12. Package outline



13. Soldering

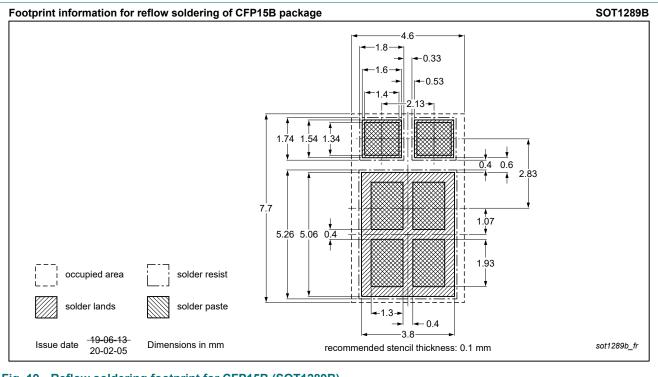


Fig. 19. Reflow soldering footprint for CFP15B (SOT1289B)

14. Revision history

Table 8. Revision history

| Data sheet ID | Release date | Data sheet status | Change notice | Supersedes | | | | |
|---------------------|-------------------|------------------------|---------------|---------------------|--|--|--|--|
| PMEG100T050ELPE v.2 | 20201203 | Product data sheet | - | PMEG100T050ELPE v.1 | | | | |
| Modifications: | Product status of | changed | | | | | | |
| PMEG100T050ELPE v.1 | 20201019 | Preliminary data sheet | - | - | | | | |

15. Legal information

Data sheet status

| Document status [1][2] | Product status [3] | Definition |
|--------------------------------|-----------------------|---|
| Objective [short] data sheet | Development | This document contains data from the objective specification for product development. |
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| Product [short] data sheet | Production | This document contains the product specification. |

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